

sub C1 25. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by applying onto a substrate a colloidal silica in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

sub C1 26. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching to a supporting face a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented.

sub C1 27. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17, the dielectric layer is formed by attaching and setting to a hollow form a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented, and then transferring the dielectric sheet to a substrate.


REMARKS

This Preliminary Amendment is submitted to improve the form of the specification as originally-filed and to delete the multiple dependent claims.

It is respectfully requested that this Preliminary Amendment be entered in the above-referenced application.

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS

Please **AMEND** the following claims:

3. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is a silica powder.

4. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is an alumina powder.

5. (ONCE AMENDED) A plasma display panel according to claim 1 [or claim 2], wherein the filler is hollow glass micro-balloons.

6. (ONCE AMENDED) A plasma display panel according to [any one of claim 1 to claim 5]claim 1, wherein the thickness of the dielectric layer is 10 μ m or less.

13. (ONCE AMENDED) A plasma display panel according to claim 7 [or claim 8] further comprising barrier ribs for partitioning a discharge space, wherein sidewalls of the barrier ribs are covered with the dielectric layer.

19. (ONCE AMENDED) A plasma display panel according to claim 7 [or claim 8], wherein a light-shielding layer is provided on a front side with respect to a discharge space and the dielectric layer is provided on a rear side with respect to the light-shielding layer.

21. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by applying onto a substrate a low-melting-point glass paste in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

25. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by applying onto a substrate a colloidal silica in which a flake-form filler for enhancing reflectance is mixed, followed by burning.

26. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by attaching to a supporting face a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented.

27. (ONCE AMENDED) A process for manufacturing a substrate structure wherein, in manufacture of the substrate structure as set forth in claim 17 [or claim 20], the dielectric layer is formed by attaching and setting to a hollow form a dielectric sheet in which a flake-form filler for enhancing reflectance is dispersed in a state such that the filler is uniformly oriented, and then transferring the dielectric sheet to a substrate.